

SOT1000-1

plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; resin based; body 6 x 5 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36R
Package type industry code	HVQFN36R
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.8	-	0.85	0.9	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	36	-	

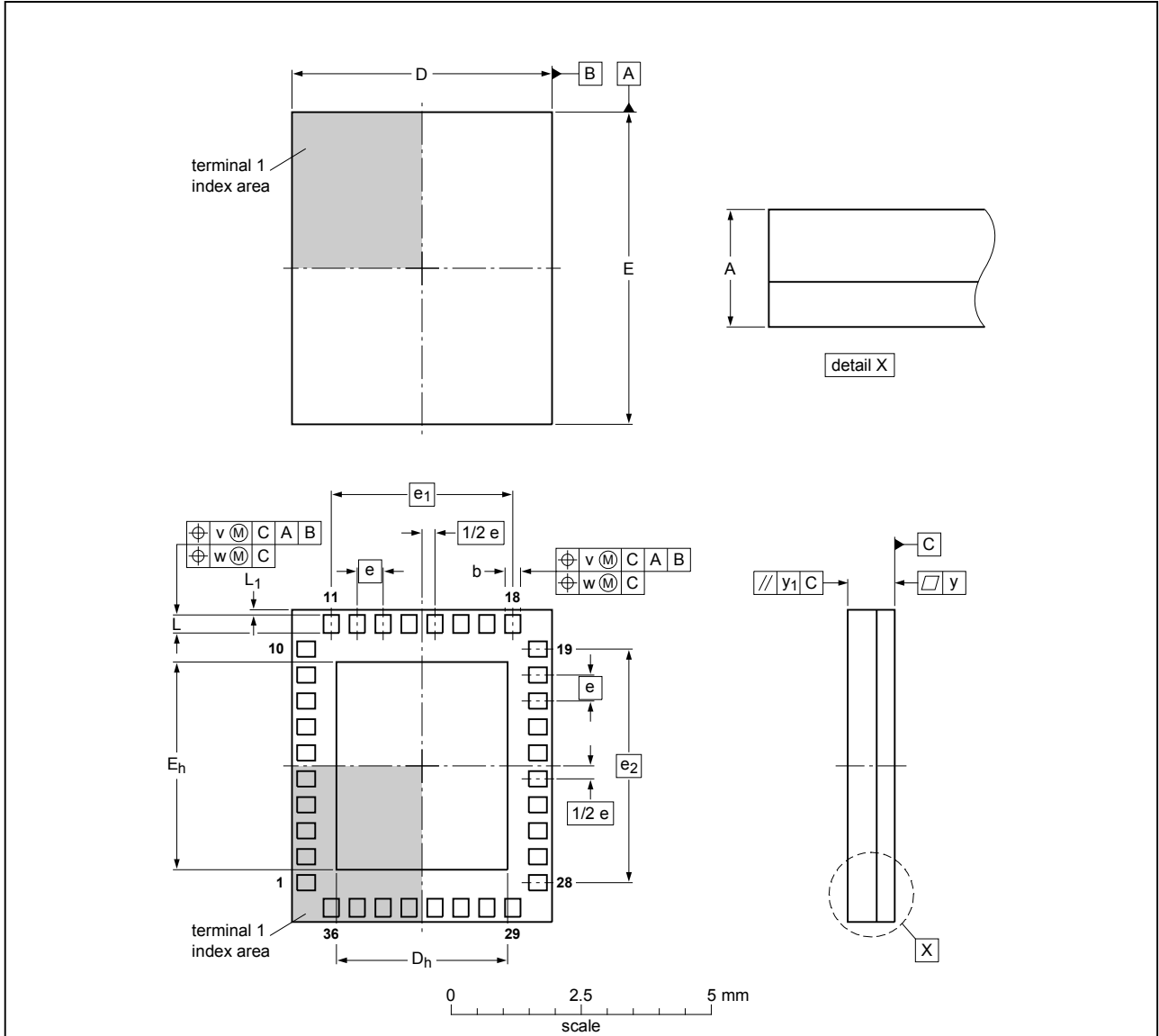


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2. Package outline

HVQFN36R: plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; resin based; body 6 x 5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT		A	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	max	0.90	0.35	5.1	3.35	6.1	4.05				0.40	0.15				
	nom	0.85	0.30	5.0	3.30	6.0	4.00	0.5	3.5	4.5	0.35	0.10	0.05	0.05	0.08	0.08
	min	0.80	0.25	4.9	3.25	5.9	3.95				0.30	0.05				

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1000-1		---	---			08-03-05 08-03-14

Fig. 1. Package outline HVQFN36R (SOT1000-1)

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3. Legal information

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